

# MOS FIELD EFFECT TRANSISTOR 2SK3405

# **SWITCHING N-CHANNEL POWER MOS FET** INDUSTRIAL USE

## **DESCRIPTION**

The 2SK3405 is N-Channel MOS FET device that features a low on-state resistance and excellent switching characteristics, designed for low voltage high current applications such as DC/DC converter with synchronous rectifier.

# **ORDERING INFORMATION**

PART NUMBER	PACKAGE
2SK3405	TO-220AB
2SK3405-ZK	TO-263(MP-25ZK)
2SK3405-ZJ	TO-263(MP-25ZJ)

# **FEATURES**

- 4.5-V drive available
- · Low on-state resistance

 $R_{DS(on)1} = 9.0 \text{ m}\Omega$  MAX. (Vgs = 10 V, ID = 24 A)

· Low gate charge

 $Q_G = 34 \text{ nC TYP}$ . (ID = 48 A, VDD = 16 V, VGS = 10 V)

- Built-in gate protection diode
- Surface mount device available

# ABSOLUTE MAXIMUM RATINGS (TA = 25℃)

Drain to Source Voltage (Vgs = 0 V)	VDSS	20	V
Gate to Source Voltage (Vps = 0 V)	Vgss	±20	V
Drain Current (DC) (Tc = 25°C)	I <sub>D(DC)</sub>	±48	Α
Drain Current (Pulse) Note	D(pulse)	±192	Α
ww.DataShar Diwer Dissipation (TA = 25°C)	P <sub>T1</sub>	1.5	W
Total Power Dissipation (Tc = 25°C)	P <sub>T2</sub>	50	W
Channel Temperature	Tch	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

**Note** PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

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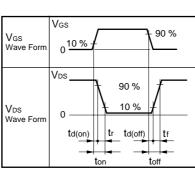
Not all devices/types available in every country. Please check with local NEC representative for availability and additional information.

**ELECTRICAL CHARACTERISTICS(TA = 25℃)** 

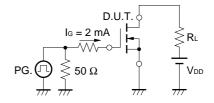
CHARACTERICTICS		TECT CONDITIONS	MINI	TVD	MAY	LINUT
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Drain Leakage Current	IDSS	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V			10	μΑ
Gate Leakage Current	Igss	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μΑ
Gate Cut-off Voltage	V <sub>GS(off)</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.5		2.5	V
Forward Transfer Admittance	yfs	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 24 A	12.5			S
Drain to Source On-state Resistance	RDS(on)1	Vgs = 10 V, ID = 24 A		6.5	9.0	mΩ
	RDS(on)2	Vgs = 4.5 V, ID = 24 A		9.9	14.0	mΩ
Input Capacitance	Ciss	V <sub>DS</sub> = 10 V		1800		pF
Output Capacitance	Coss	Vgs = 0 V		770		pF
Reverse Transfer Capacitance	Crss	f = 1 MHz		400		pF
Turn-on Delay Time	td(on)	V <sub>DD</sub> = 10 V , I <sub>D</sub> = 24 A		21		ns
Rise Time	tr	$V_{GS(on)} = 10 \text{ V}$		13		ns
Turn-off Delay Time	td(off)	$R_G = 10 \Omega$		64		ns
Fall Time	t <sub>f</sub>			25		ns
Total Gate Charge	Q <sub>G</sub>	V <sub>DD</sub> = 16 V		34		nC
Gate to Source Charge	Qgs	Vgs = 10 V		6.6		nC
Gate to Drain Charge	Q <sub>GD</sub>	ID = 48 A		11		nC
Diode Forward Voltage	V <sub>F(S-D)</sub>	IF = 48 A, VGS = 0 V		1.0		V
Reverse Recovery Time	trr	IF = 48 A, VGS = 0 V		38		ns
Reverse Recovery Charge	Qrr	di/dt = 100 A/μs		29		nC

# **TEST CIRCUIT 1 SWITCHING TIME**

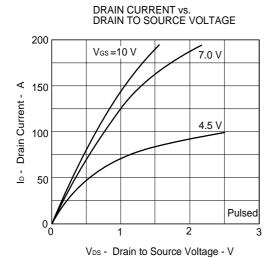
# D.U.T. PG. RG RG Wave Form $\tau = 1 \mu s$ Duty Cycle $\leq 1 \%$

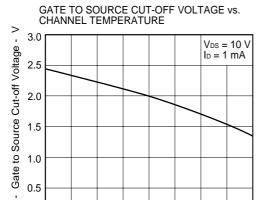


# **TEST CIRCUIT 2 GATE CHARGE**



# TYPICAL CHARACTERISTICS (TA = 25°C)





50 100 Tch - Channel Temperature - °C

150



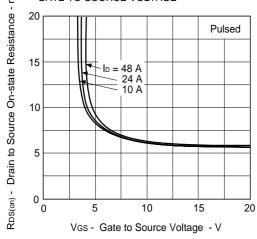
0

0.5

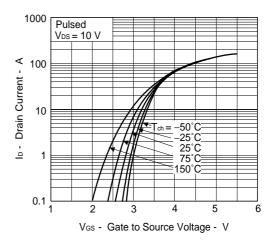
0

-50

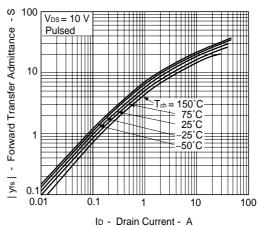
Vgs(off)

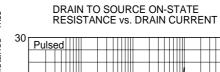


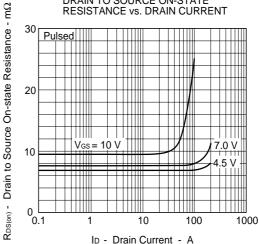
### FORWARD TRANSFER CHARACTERISTICS

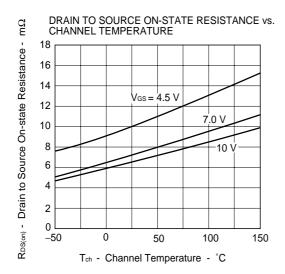


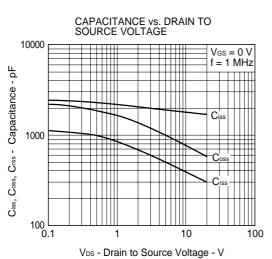
FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

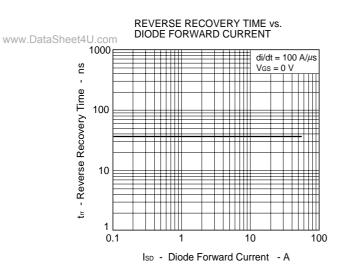




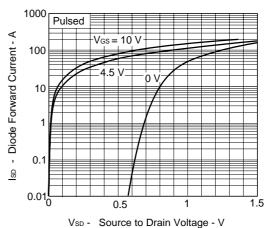




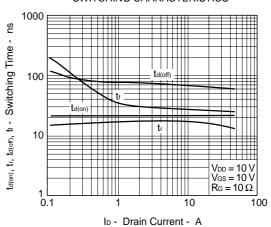




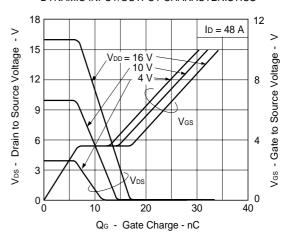
# SOURCE TO DRAIN DIODE FORWARD VOLTAGE

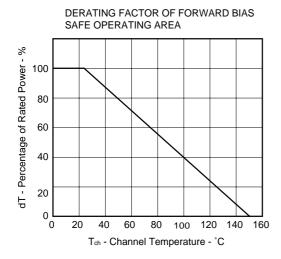


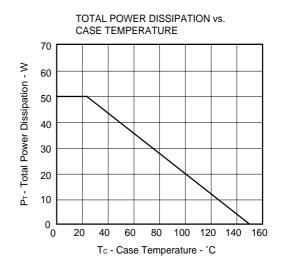
### SWITCHING CHARACTERISTICS



# DYNAMIC INPUT/OUTPUT CHARACTERISTICS



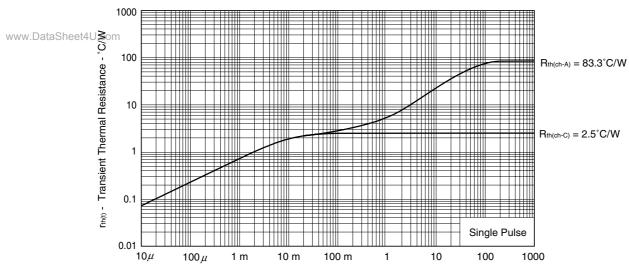




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VDS - Drain to Source Voltage - V

### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

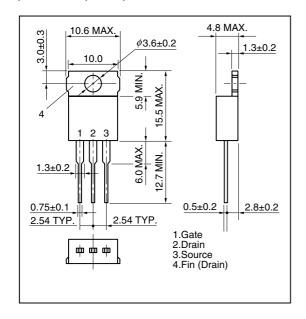


PW - Pulse Width - sec

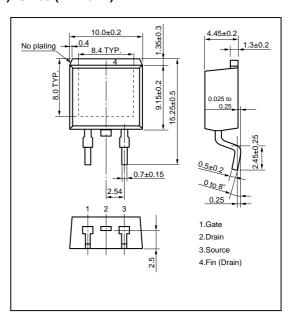


# **PACKAGE DRAWINGS (Unit: mm)**

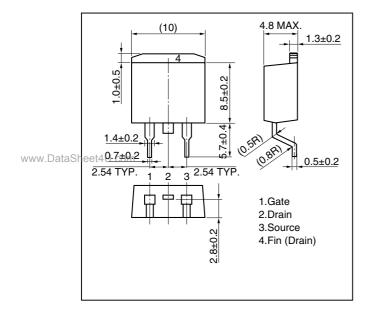
# 1)TO-220AB (MP-25)



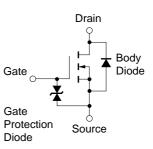
# 2)TO-263 (MP-25ZK)



# 3)TO-263 (MP-25ZJ)



# **EQUIVALENT CIRCUIT**



**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

[MEMO]

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